

STM32WL_BGA73_Ref_Board_with_TCXO

MB1842

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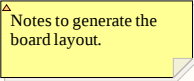
- Sheet 1: Project overview (this page)
- Sheet 2: STM32WL_BGA73_Ref_Board_with_TCXO.SchDoc

Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



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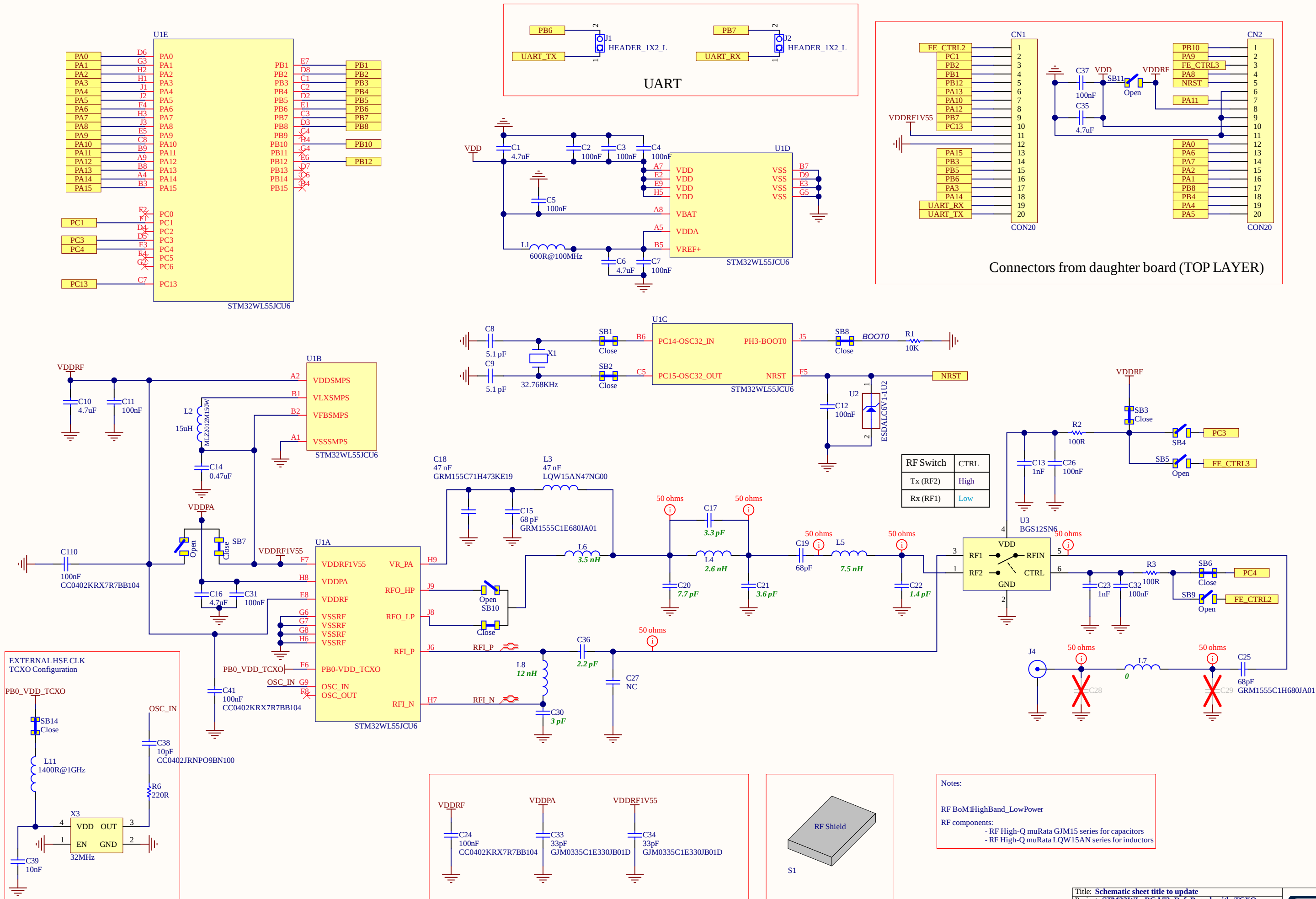
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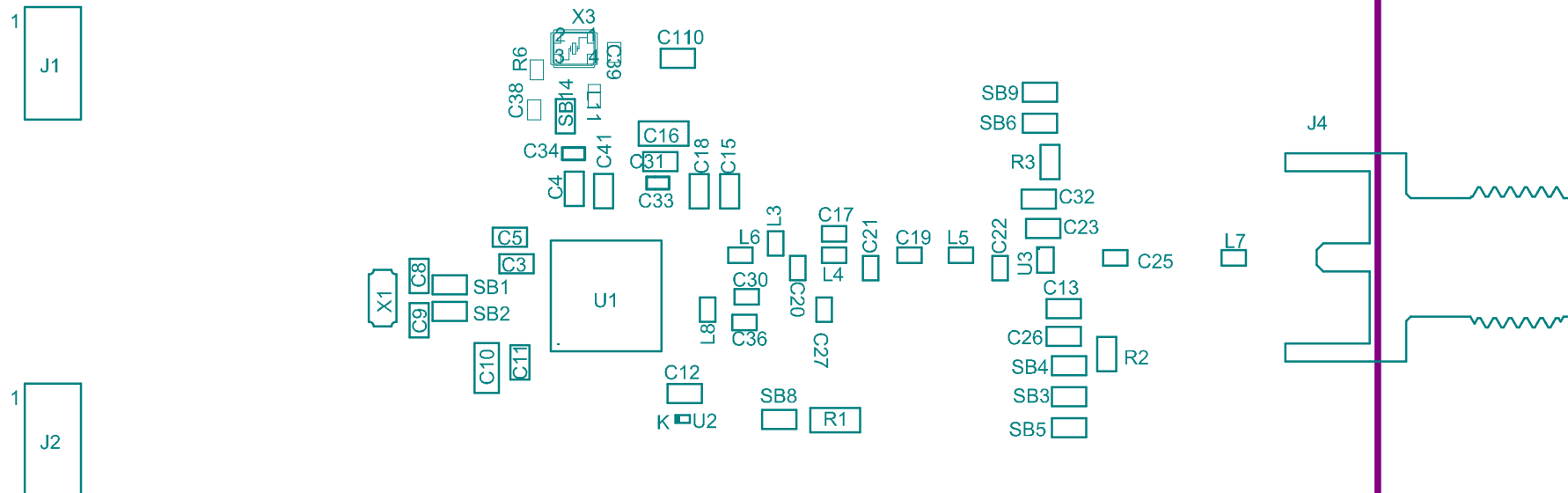
U_Top
STM32WL_BGA73_Ref_Board_with_TCXO.SchDoc



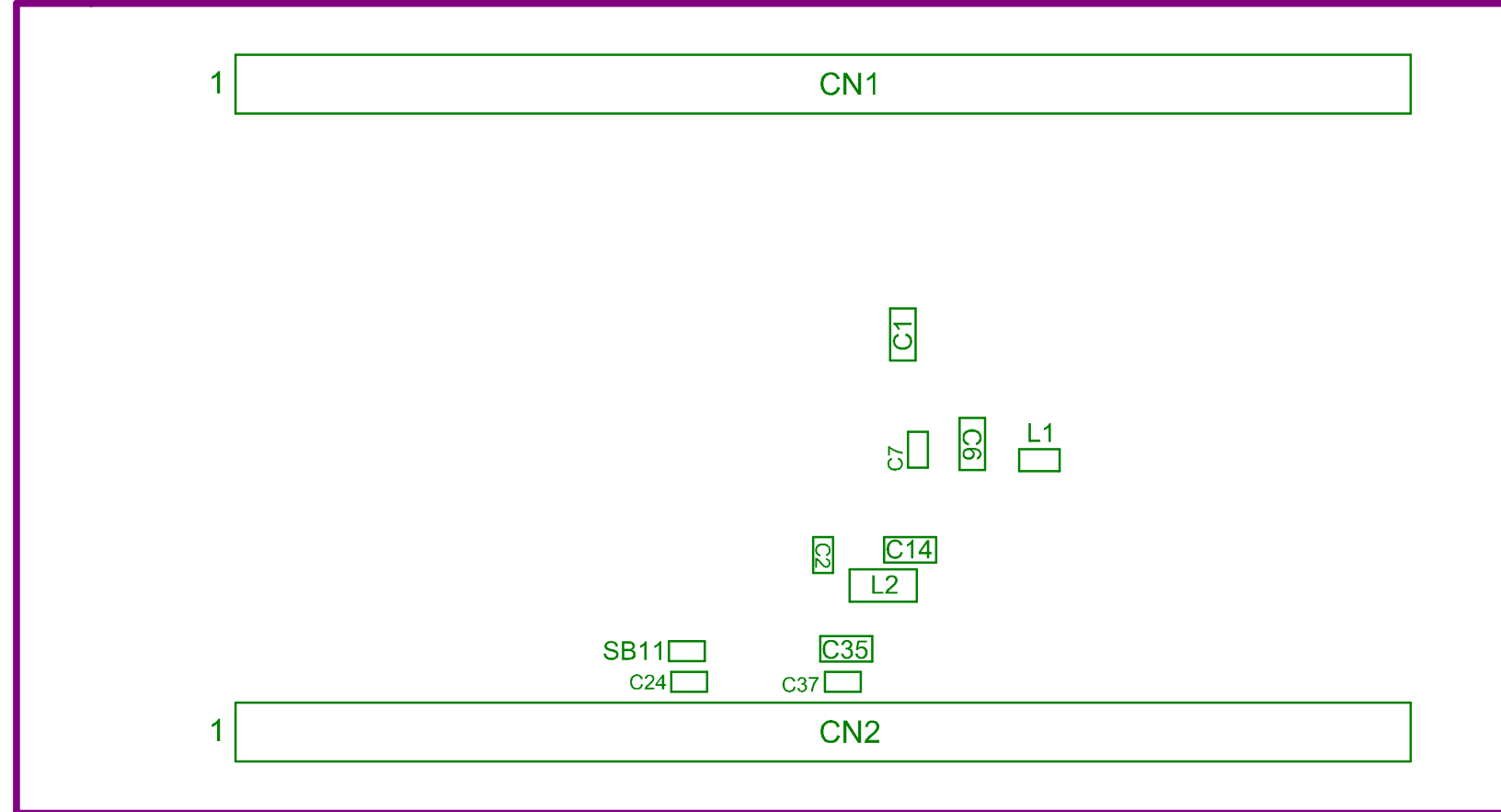
Title: Schematic sheet title to update		
Project: STM32WL_BGA73_Ref_Board_with_TCXO		
Variant: HighBand_LowPower		
Revision: A-01	Reference: MB1842	
Size: A4	Date: 23-03-2022	Sheet: 1 of 2



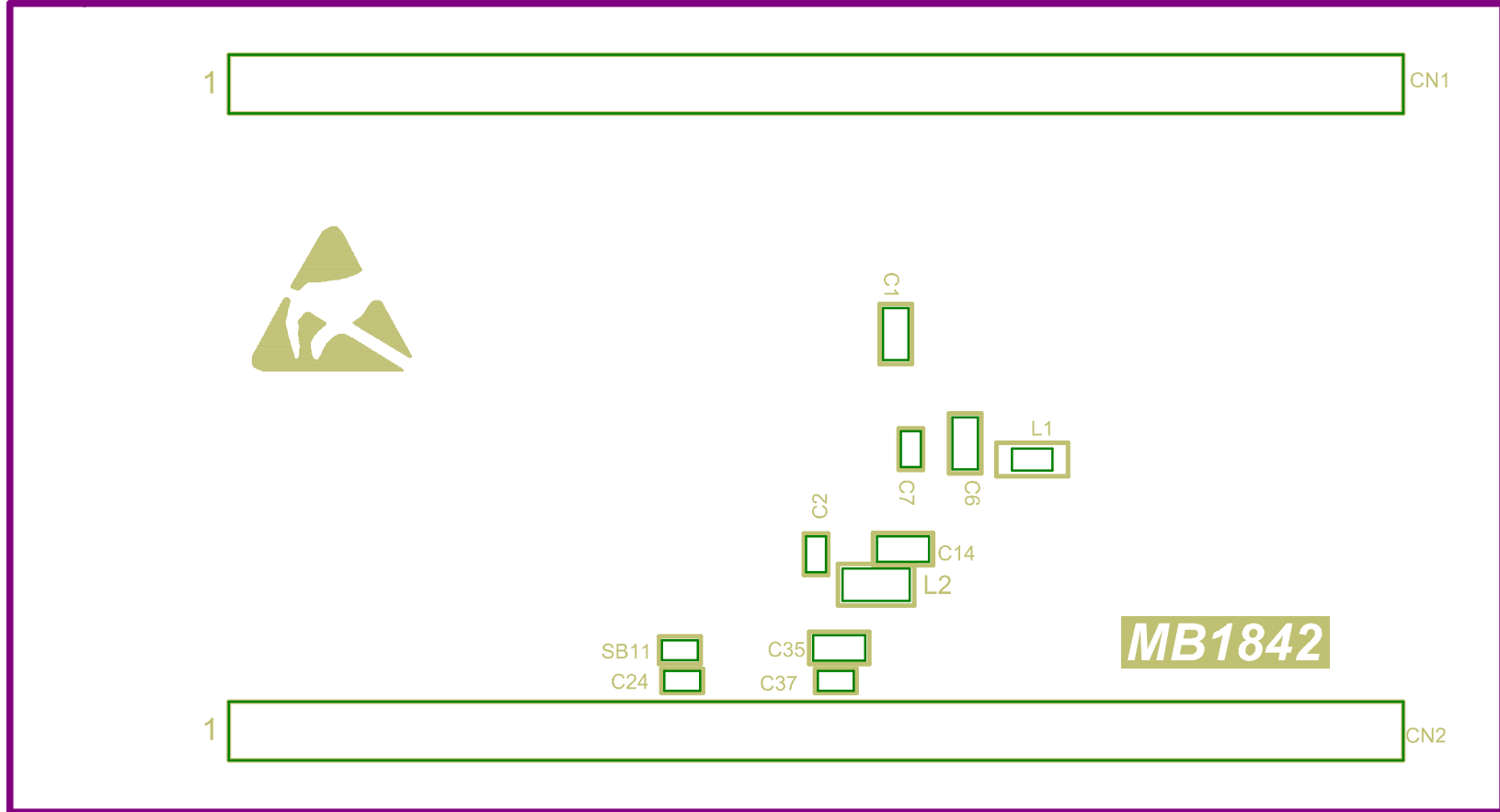




Project: STM32WL_BGA73_Ref_Board_with_TCXO		
Layer: Top Assembly	Gerber: .GM14	
Variant: HighBand_LowPower	Ref: MB1842	
Date: 23-03-2022	Rev: A	



Project: STM32WL_BGA73_Ref_Board_with_TCXO		
Layer: Bottom Assembly	Gerber: .GM15	
Variant: HighBand_LowPower	Ref: MB1842	
Date: 23-03-2022	Rev: A	



Bottom Overlay

.GBO